



Shenzhen Tuofeng Semiconductor Technology Co., Ltd

**N - CHANNEL ENHANCEMENT MODE POWER MOSFET****TFD040N03N****• General Description**

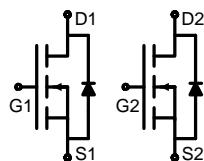
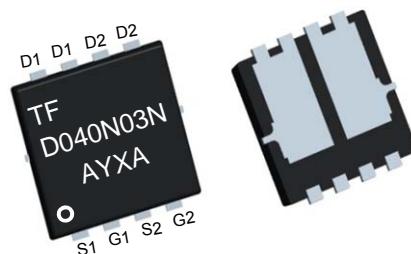
The TFD040N03N combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ . This device is ideal for load switch and battery protection applications.

**• Features**

- Advance high cell density Trench technology
- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

**• Application**

- MB/VGA Vcore
- SMPS 2<sup>nd</sup> Synchronous Rectifier
- POL application
- BLDC Motor driver

**• Product Summary** $V_{DS} = 30V \quad I_D = 60A$  $R_{DS(ON)(10V\ typ)} = 5.5m\Omega$  $R_{DS(ON)(4.5V\ typ)} = 7.3m\Omega$ **PDFNWB5x6-8L****• Ordering Information:**

Part NO.	TFD040N03N
Marking 1	D040N03N
Marking 2	TF:tuofeng; AA:device code; Y:year code; X:Week
MOQ	5000

**• Absolute Maximum Ratings ( $T_C = 25^\circ C$ )**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D @ T_C = 25^\circ C$	60	A
	$I_D @ T_C = 75^\circ C$	42	A
	$I_D @ T_C = 100^\circ C$	36	A
Pulsed Drain Current <sup>①</sup>	$I_{DM}$	180	A
Total Power Dissipation	$P_D @ T_C = 25^\circ C$	50	W
Total Power Dissipation	$P_D @ T_A = 25^\circ C$	2.0	W
Operating Junction Temperature	$T_J$	-55 to 150	$^\circ C$
Storage Temperature	$T_{STG}$	-55 to 150	$^\circ C$

Note: ① Pulse Test : Pulse width  $\leq 300\mu s$ , Duty cycle  $\leq 2\%$  ;



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## N - CHANNEL ENHANCEMENT MODE POWER MOSFET

TFD040N03N

Single Pulse Avalanche Energy	$E_{AS}$	90	mJ
Avalanche Current	$I_{AS} I_{AR}$	20	A

## •Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	$R_{thJC}$	-	-	4.3	° C/W
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	58	° C/W
Soldering temperature, wave soldering for 8s	$T_{sold}$	-	-	265	° C

## •Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	1.0	1.5	2.5	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS} = 30V, V_{GS} = 0V$			1.0	$\mu A$
Gate- Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 20A$		5.5	7.0	$m\Omega$
		$V_{GS} = 4.5V, I_D = 15A$		7.3	9.0	$m\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS} = 25V, I_D = 20A$		15		S
Source-drain voltage	$V_{SD}$	$I_S = 20A$			1.20	V

## •Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	$C_{iss}$	$V_{DS} = 15V, V_{GS} = 0V$ $f = 1MHz$	-	2700	-	pF
Output capacitance	$C_{oss}$		-	321	-	
Reverse transfer capacitance	$C_{rss}$		-	245	-	

•Gate Charge characteristics( $T_a = 25^\circ C$ )

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Gate Resistance	$R_g$	$f = 1MHz$		1.5		$\Omega$
Total gate charge	$Q_g$	$V_{DD} = 15V$	-	42	-	nC
Gate - Source charge	$Q_{gs}$		-	4.0	-	
Gate - Drain charge	$Q_{gd}$		-	14	-	
Turn-ON Delay time	$t_{D(on)}$	$V_{GS} = 10V, V_{DS} = 10V$ $R_G = 3.0\Omega, I = 20A$		13		ns
Turn-ON Rise time	$t_r$			36		ns
Turn-Off Delay time	$t_{D(off)}$			43		ns
Turn-Off Fall time	$t_f$			16		ns

Fig.1 Power Dissipation

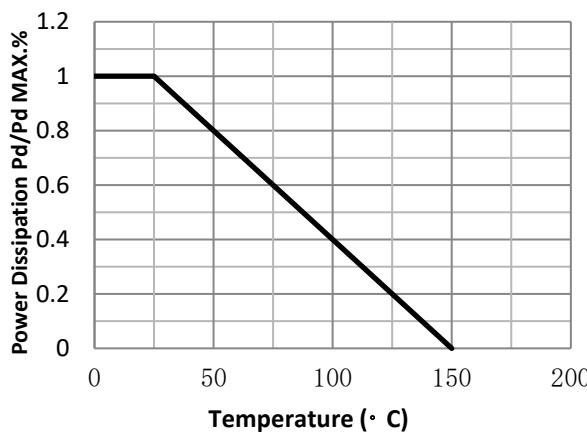


Fig.2 Typical output Characteristics

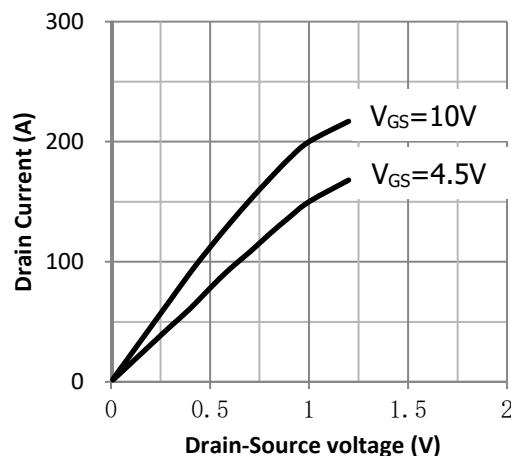


Fig.3 Threshold Voltage V.S Junction Temperature

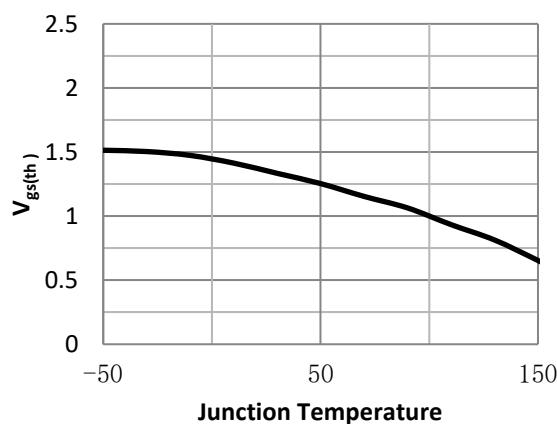


Fig.4 Resistance V.S Drain Current

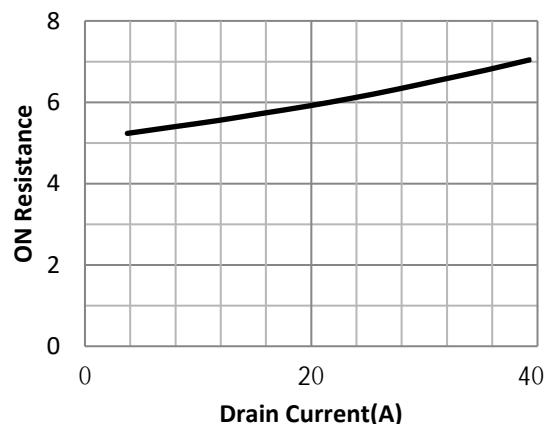


Fig.5 On-Resistance VS Gate Source Voltage

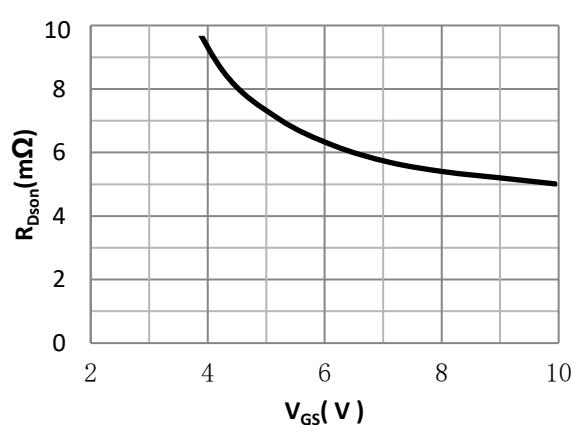


Fig.6 On-Resistance V.S Junction Temperature

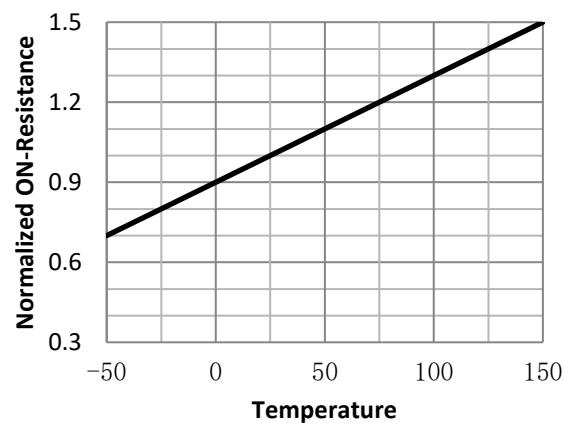


Fig.7 Switching Time Measurement Circuit

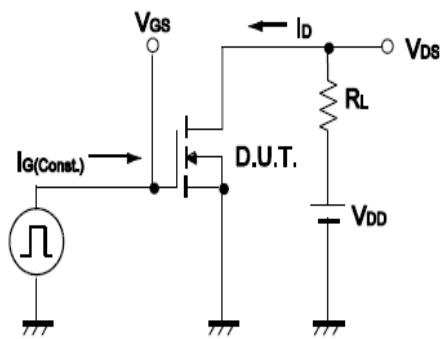


Fig.8 Gate Charge Waveform

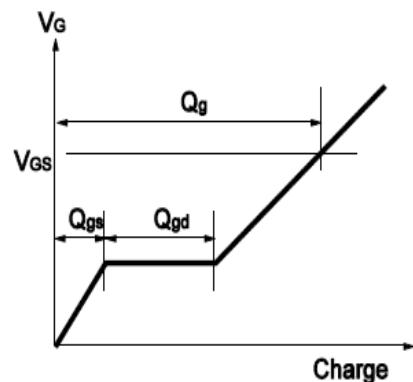


Fig.9 Switching Time Measurement Circuit

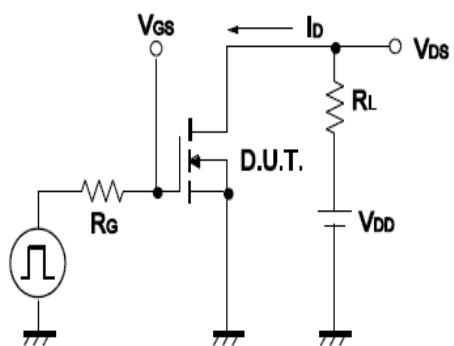


Fig.10 Gate Charge Waveform

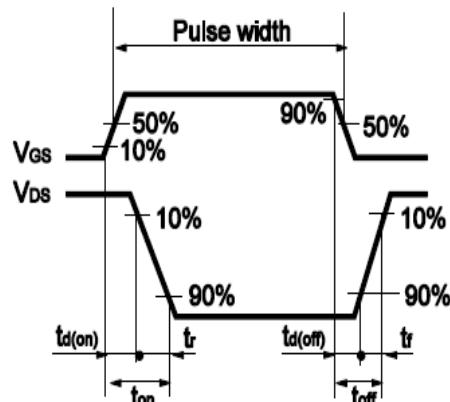


Fig.11 Avalanche Measurement Circuit

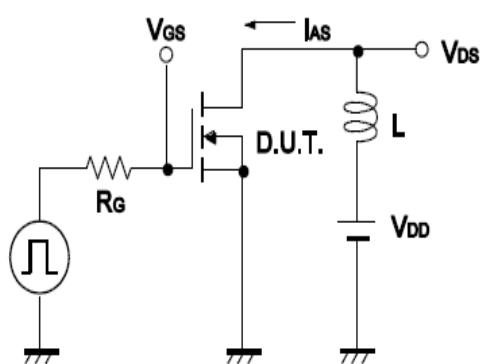
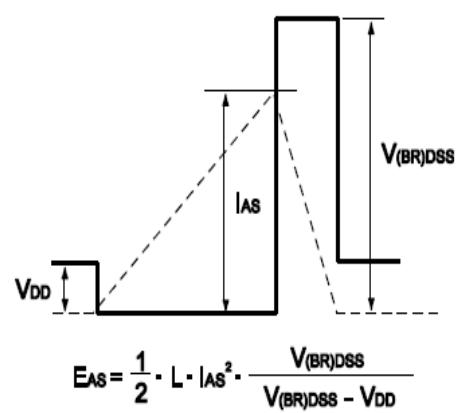


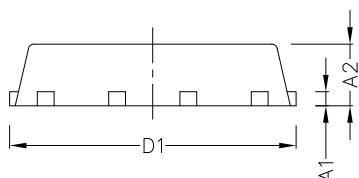
Fig.12 Avalanche Waveform



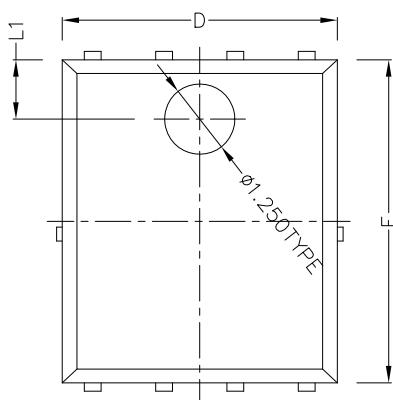


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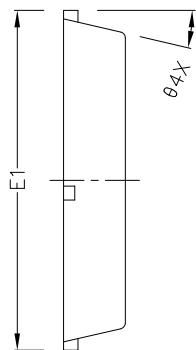
## N-CHANNEL ENHANCEMENT MODE POWER MOSFET

**TFD040N03N****PDFNWB5x6-8L Package Outline Dimensions**

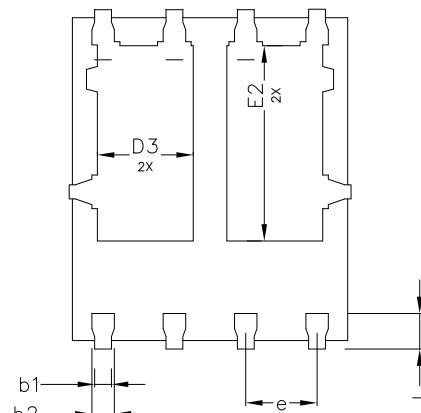
SIDE VIEW



TOP VIEW



SIDE VIEW

BOTTOM VIEW  
OPTION

COMMON DIMENSIONS (UNITS OF MEASURE IS mm)			
	MIN	NORMAL	MAX
A1		0.254 BSC	
A2	1.000	1.100	1.200
b1	0.250	0.300	0.350
b2	0.350	0.400	0.450
D	4.800	4.900	5.000
D1	5.000	5.100	5.200
D2	3.910	4.010	4.110
D3	1.605	1.705	1.805
E	5.650	5.750	5.850
E1	5.950	6.050	6.150
E2	3.375	3.475	3.575
e	1.270 TYPE		
L	0.530	0.630	0.730
L1	1.00REF		
θ	13° TYPE		

## Note:

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05$ mm.
3. The pad layout is for reference purposes only.